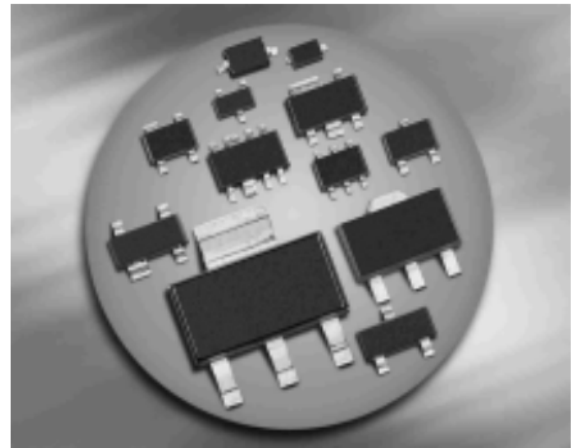
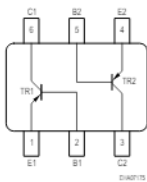


PNP Silicon Switching Transistors

- High DC current gain: 0.1 mA to 100 mA
- Low collector-emitter saturation voltage
- For SMBT3906S and SMBT3906U:
Two (galvanic) internal isolated transistor with good matching in one package
- Complementary types:
SMBT3904...MMBT3904 (NPN)
- SMBT3904S / U: for orientation in reel
see package information below



SMBT3906S/U



Type	Marking	Pin Configuration						Package
SMBT3906/ MMBT3906	s2A	1=B	2=E	3=C	-	-	-	SOT23
SMBT3906L3	2A	1=B	2=E	3=C	-	-	-	TSLP-3-4
SMBT3906S	s2A	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
SMBT3906U	s2A	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SC74

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	40	V
Collector-base voltage	V_{CBO}	40	
Emitter-base voltage	V_{EBO}	6	
Collector current	I_C	200	mA
Total power dissipation-	P_{tot}		K/W
$T_S \leq 71^\circ\text{C}$		330	
$T_S \leq t_{bd}^\circ\text{C}$		250	
$T_S \leq 115^\circ\text{C}$		250	
$T_S \leq 105^\circ\text{C}$		330	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ SMBT3906/ MMBT3906 SMBT3906L3 SMBT3906S SMBT3906U	R_{thJS}	≤ 240 $\leq tbd$ ≤ 140 ≤ 135	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Collector-emitter breakdown voltage $I_C = 1\text{ mA}$, $I_B = 0$	$V_{(BR)CEO}$	40	-	-	V
Collector-base breakdown voltage $I_C = 10\text{ }\mu\text{A}$, $I_E = 0$	$V_{(BR)CBO}$	40	-	-	
Emitter-base breakdown voltage $I_E = 10\text{ }\mu\text{A}$, $I_C = 0$	$V_{(BR)EBO}$	6	-	-	
Collector-base cutoff current $V_{CB} = 30\text{ V}$, $I_E = 0$	I_{CBO}	-	-	50	nA
DC current gain ²⁾ $I_C = 100\text{ }\mu\text{A}$, $V_{CE} = 1\text{ V}$ $I_C = 1\text{ mA}$, $V_{CE} = 1\text{ V}$ $I_C = 10\text{ mA}$, $V_{CE} = 1\text{ V}$ $I_C = 50\text{ mA}$, $V_{CE} = 1\text{ V}$ $I_C = 100\text{ mA}$, $V_{CE} = 1\text{ V}$	h_{FE}	60 80 100 60 30	- - - - -	- - 300 - -	-
Collector-emitter saturation voltage ²⁾ $I_C = 10\text{ mA}$, $I_B = 1\text{ mA}$ $I_C = 50\text{ mA}$, $I_B = 5\text{ mA}$	V_{CEsat}	- -	- -	0.25 0.4	V
Base emitter saturation voltage ²⁾ $I_C = 10\text{ mA}$, $I_B = 1\text{ mA}$ $I_C = 50\text{ mA}$, $I_B = 5\text{ mA}$	V_{BEsat}	0.65 -	- -	0.85 0.95	

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

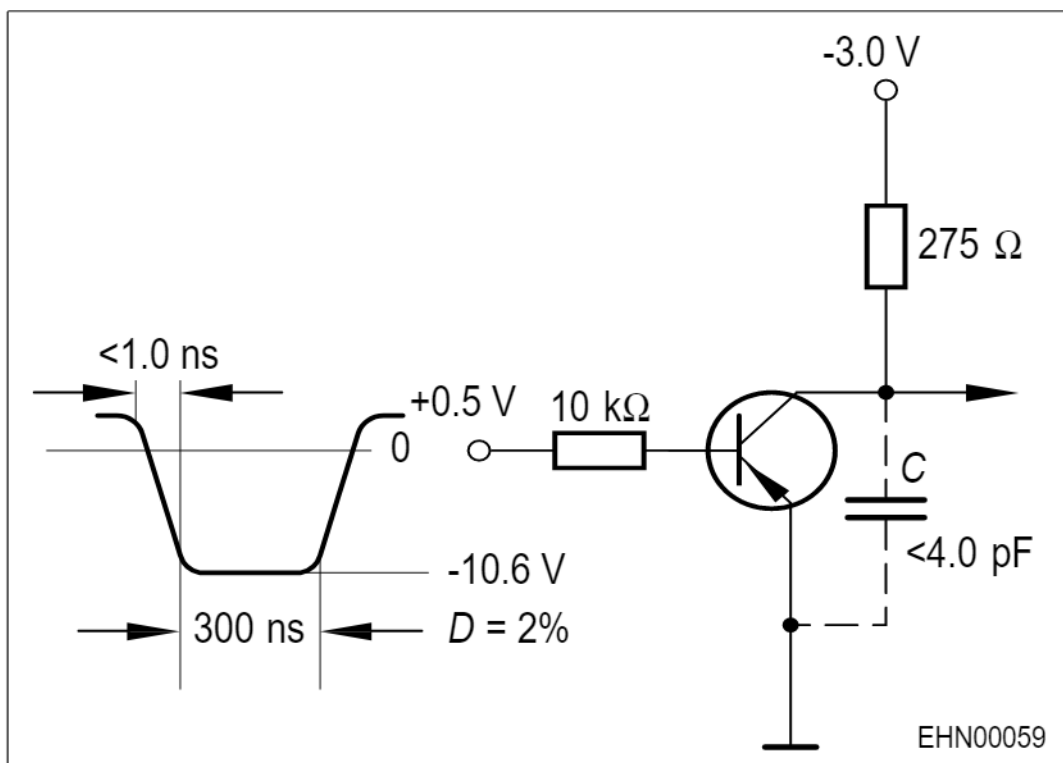
²⁾Pulse test: $t < 300\mu\text{s}$; $D < 2\%$

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

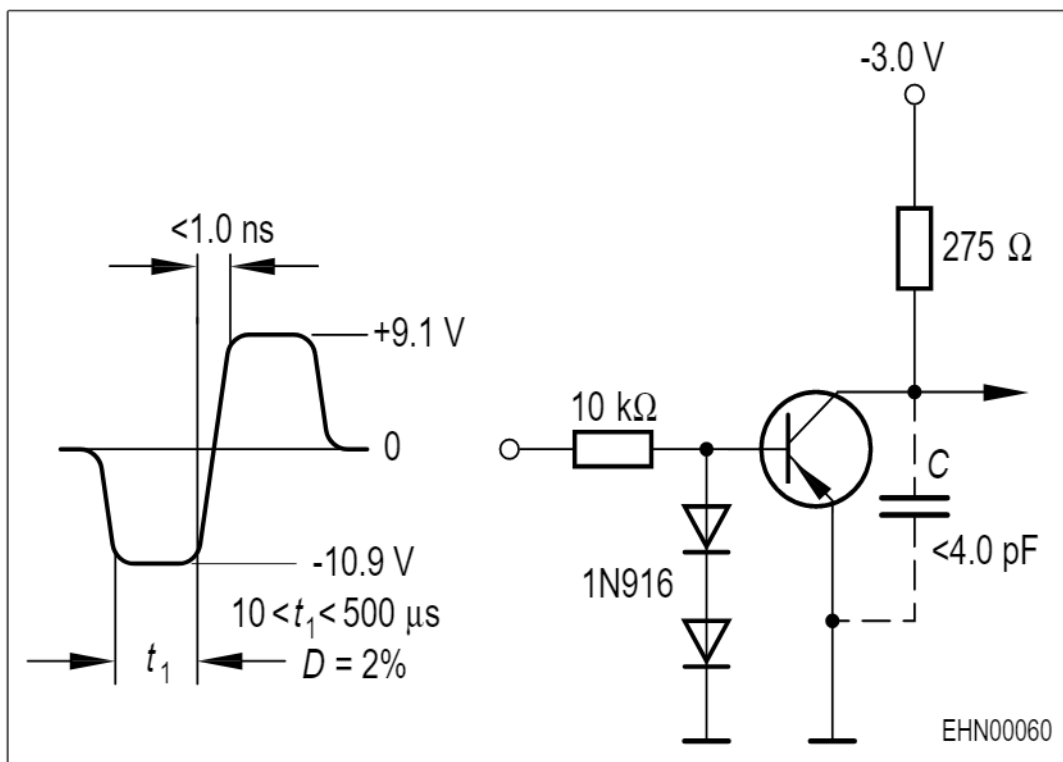
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Transition frequency $I_C = 10\text{ mA}$, $V_{CE} = 20\text{ V}$, $f = 100\text{ MHz}$	f_T	250	-	-	MHz
Collector-base capacitance $V_{CB} = 5\text{ V}$, $f = 1\text{ MHz}$	C_{cb}	-	-	3.5	pF
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$, $f = 1\text{ MHz}$	C_{eb}	-	-	10	
Delay time $V_{CC} = 3\text{ V}$, $I_C = 10\text{ mA}$, $I_{B1} = 1\text{ mA}$, $V_{BE(off)} = 0.5\text{ V}$	t_d	-	-	35	ns
Rise time $V_{CC} = 3\text{ V}$, $I_C = 10\text{ mA}$, $I_{B1} = 1\text{ mA}$, $V_{BE(off)} = 0.5\text{ V}$	t_r	-	-	35	
Storage time $V_{CC} = 3\text{ V}$, $I_C = 10\text{ mA}$, $I_{B1} = I_{B2} = 1\text{ mA}$	t_{stg}	-	-	225	
Fall time $V_{CC} = 3\text{ V}$, $I_C = 10\text{ mA}$, $I_{B1} = I_{B2} = 1\text{ mA}$	t_f	-	-	75	
Noise figure $I_C = 100\text{ }\mu\text{A}$, $V_{CE} = 5\text{ V}$, $f = 1\text{ kHz}$, $\Delta f = 200\text{ Hz}$, $R_S = 1\text{ k}\Omega$	F	-	-	4	dB

Test circuit

Delay and rise time

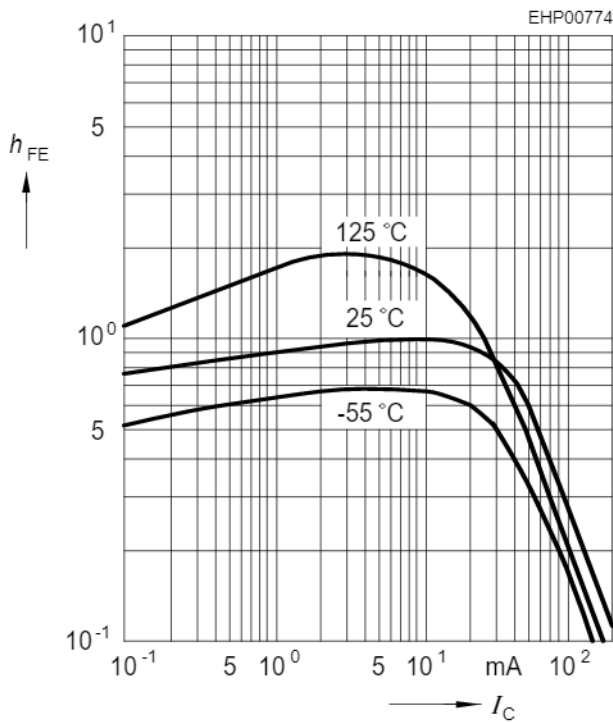


Storage and fall time



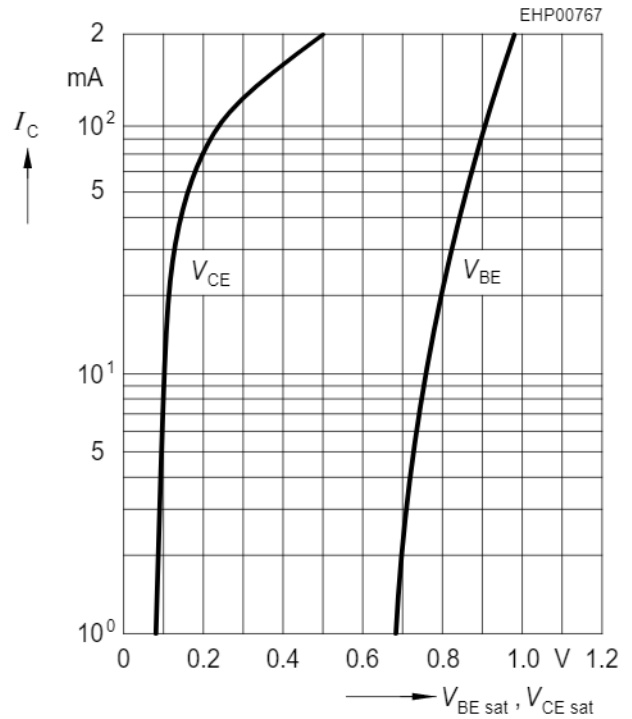
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 1\text{ V}$



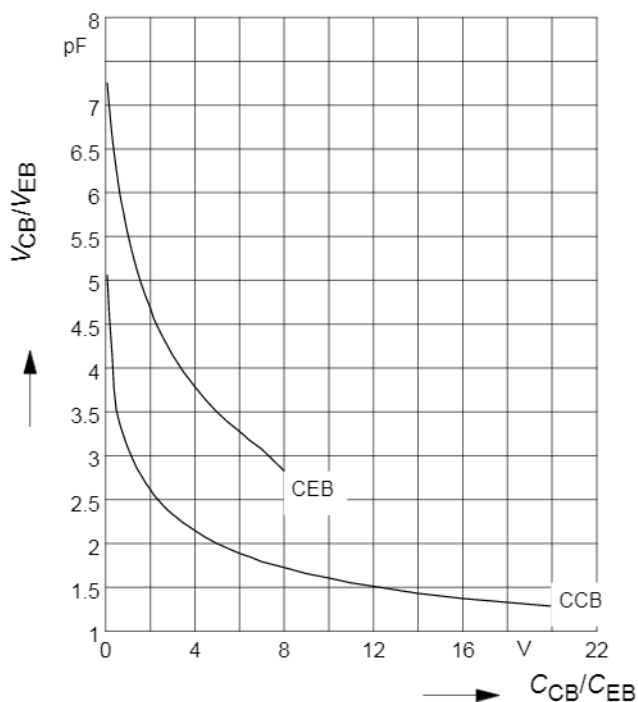
Saturation voltage $I_C = f(V_{BEsat}, V_{CEsat})$

$h_{FE} = 10$



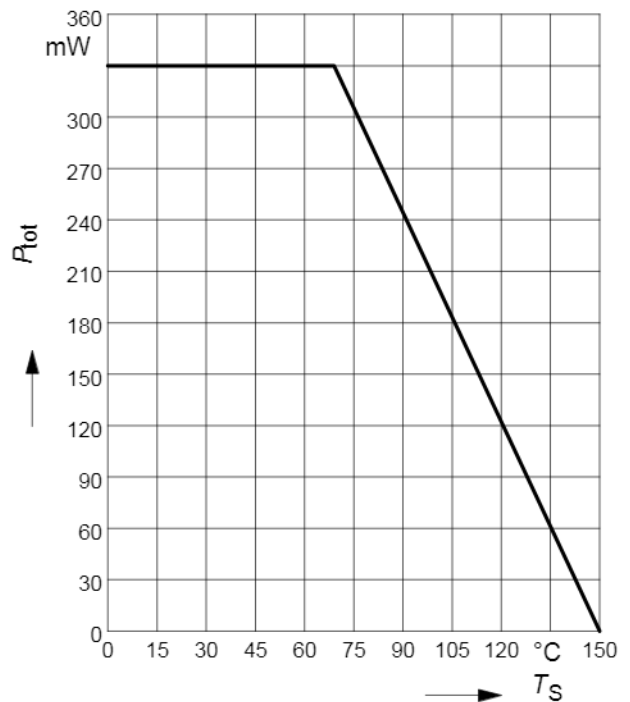
Collector-base capacitance $C_{cb} = f(V_{CB})$

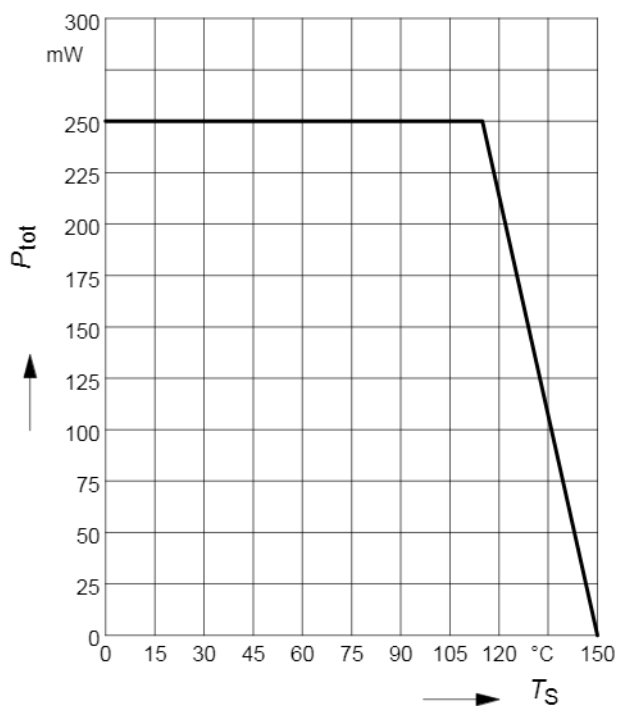
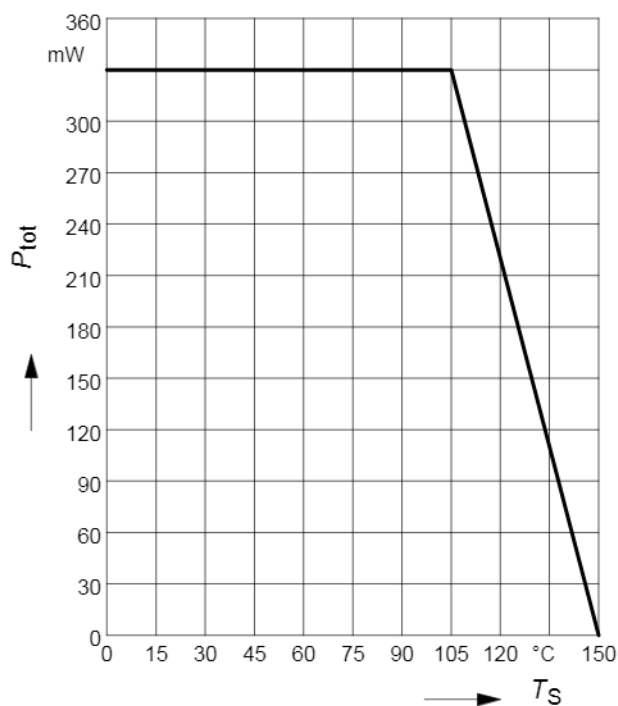
Emitter-base capacitance $C_{eb} = f(V_{EB})$



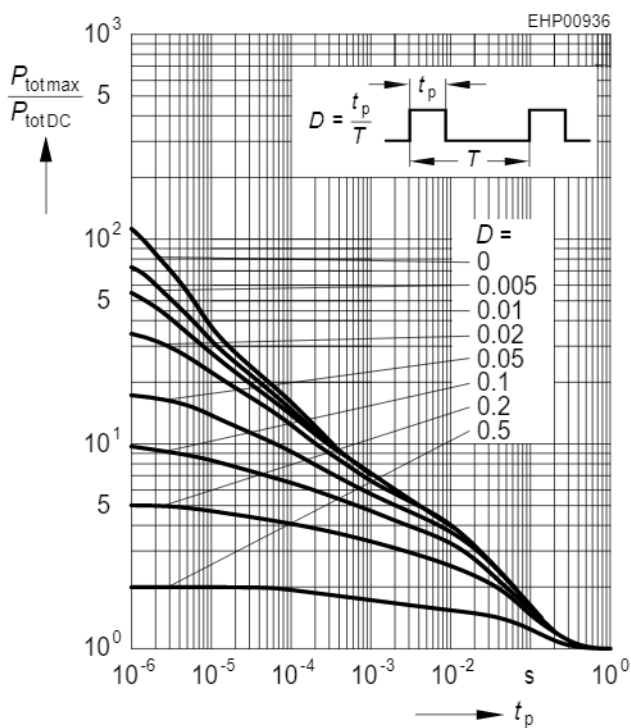
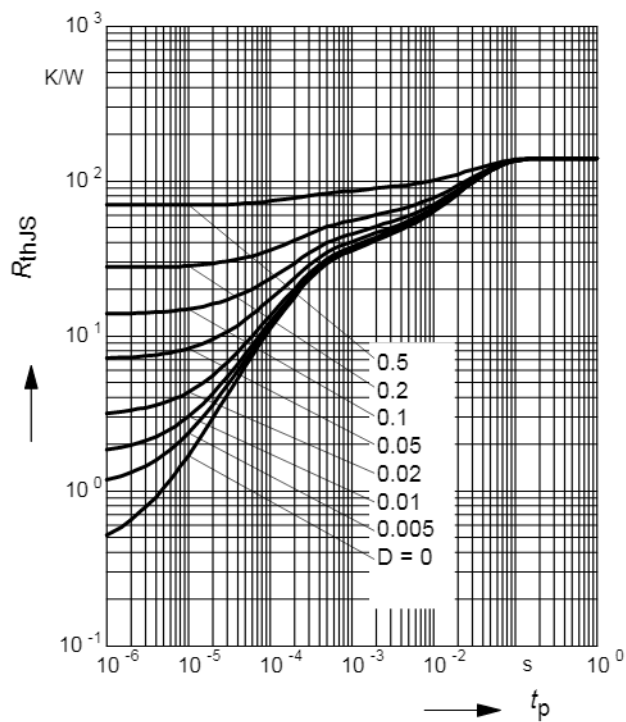
Total power dissipation $P_{tot} = f(T_S)$

SMBT3906/ MMBT3906



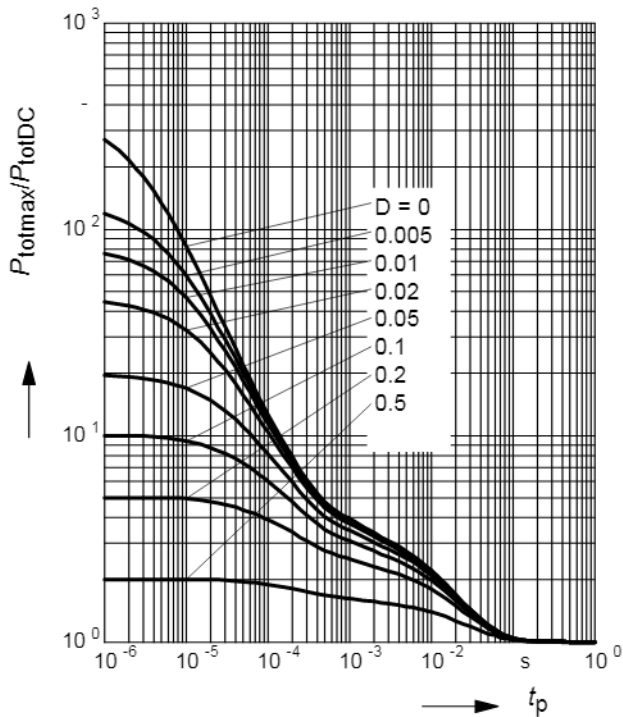
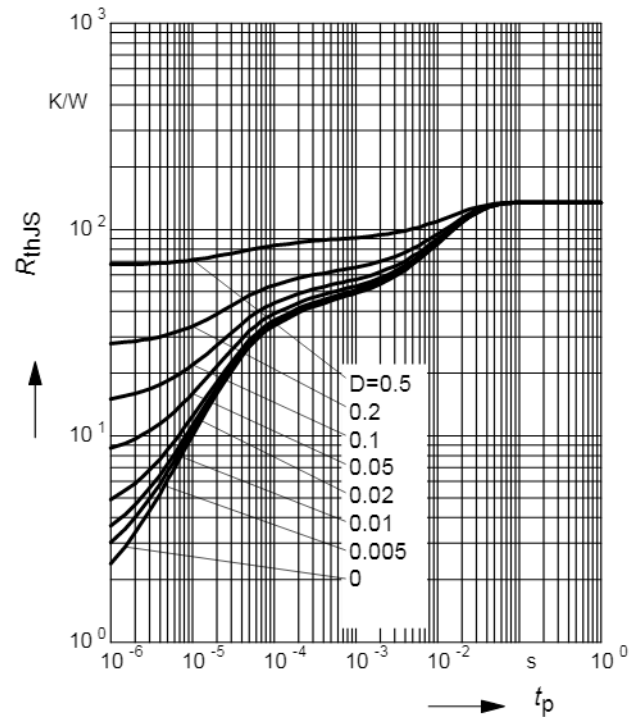
Total power dissipation $P_{\text{tot}} = f(T_S)$
SMBT3906S

Total power dissipation $P_{\text{tot}} = f(T_S)$
SMBT3906U

Permissible Pulse Load

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

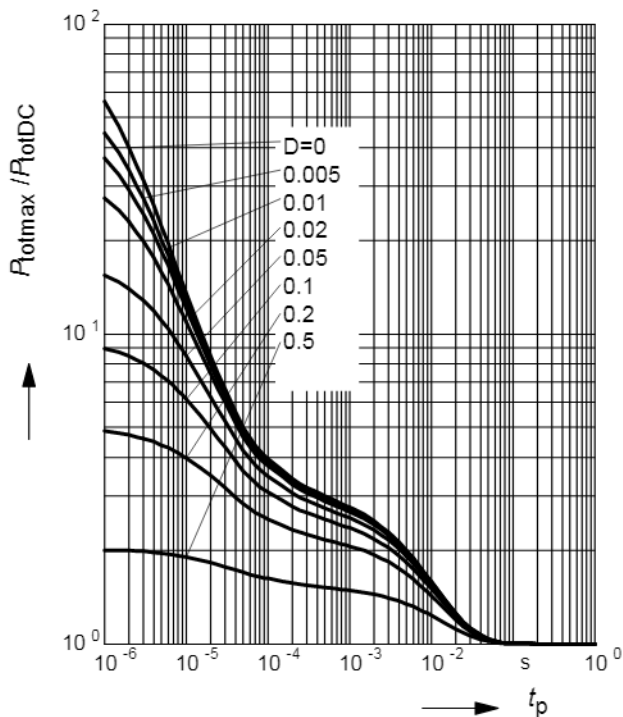
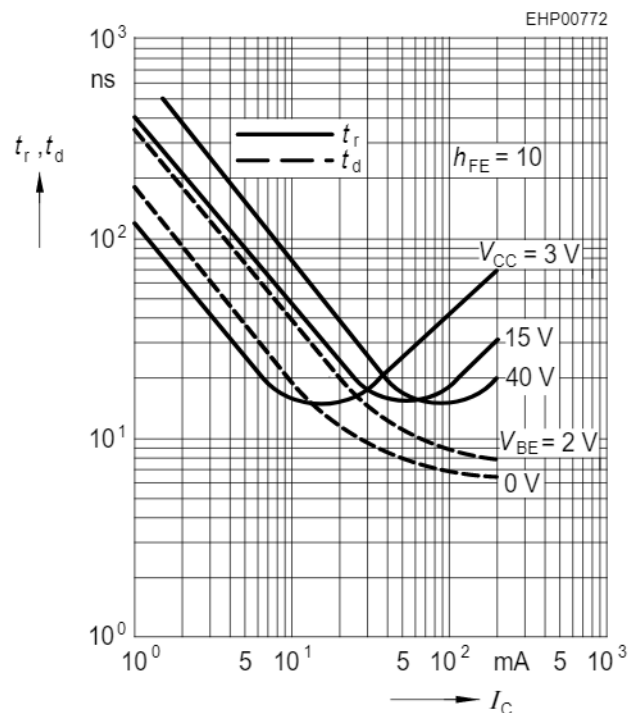

Permissible Puls Load $R_{\text{thJS}} = f(t_p)$
SMBT3906S


Permissible Pulse Load

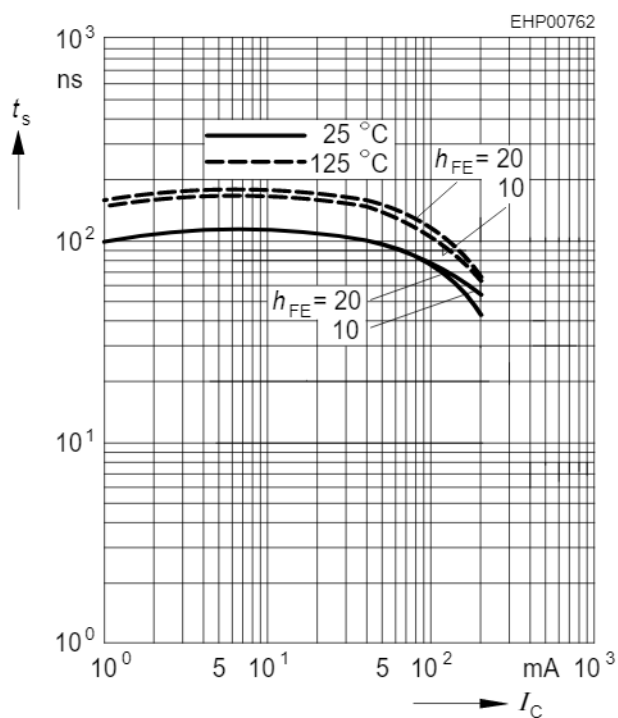
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

SMBT3906S

Permissible Puls Load $R_{\text{thJS}} = f(t_p)$
SMBT3906U

Permissible Pulse Load

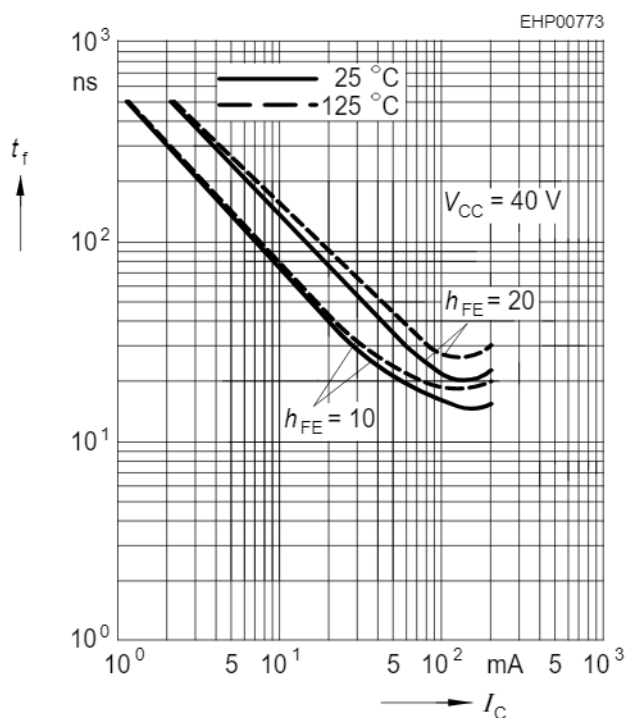
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

SMBT3906U

Delay time $t_d = f(I_C)$
Rise time $t_r = f(I_C)$


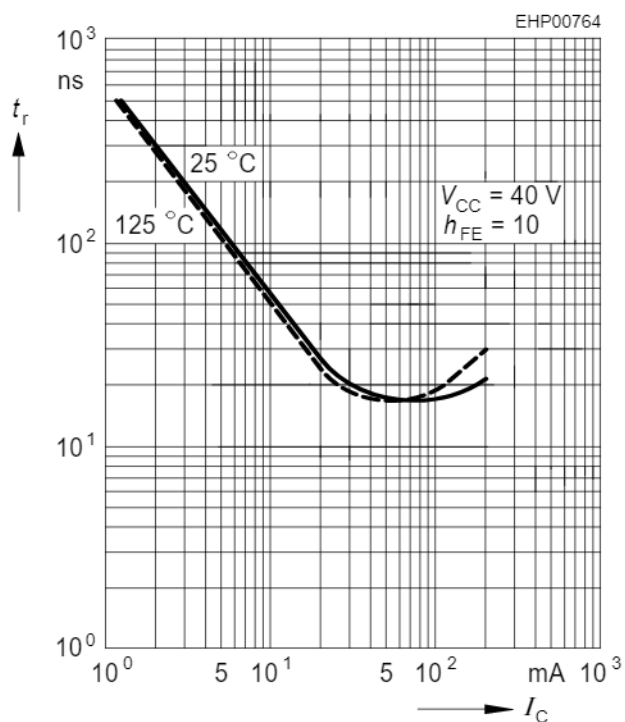
Storage time $t_{stg} = f(I_C)$



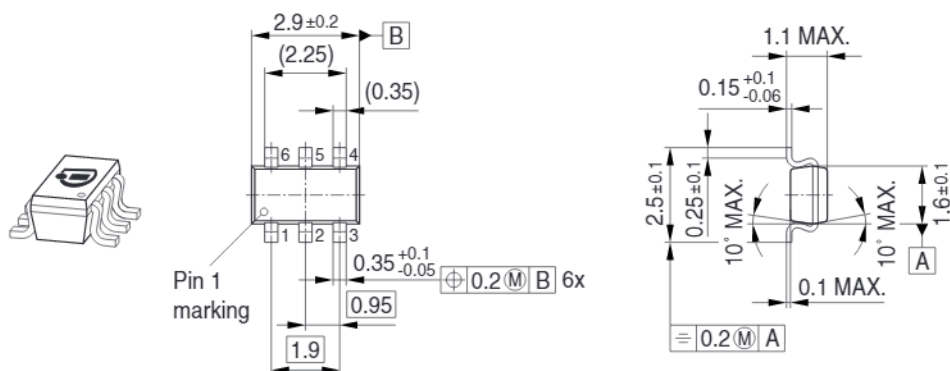
Fall time $t_f = f(I_C)$



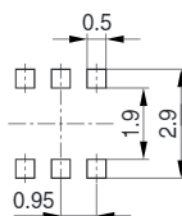
Rise time $t_r = f(I_C)$



Package Outline

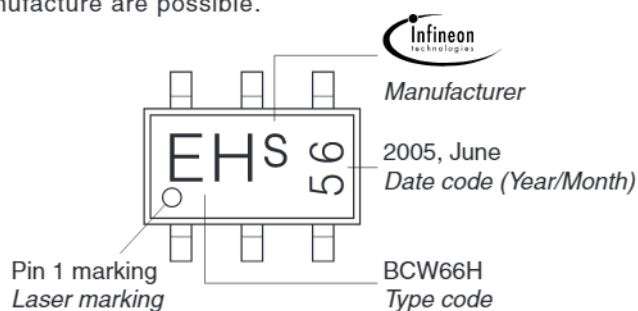


Foot Print



Marking Layout (Example)

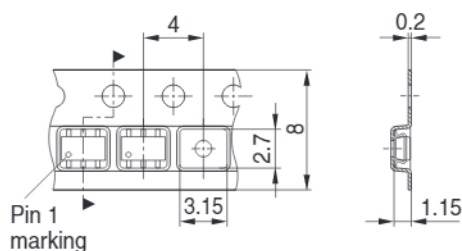
Small variations in positioning of
Date code, Type code and Manufacture are possible.



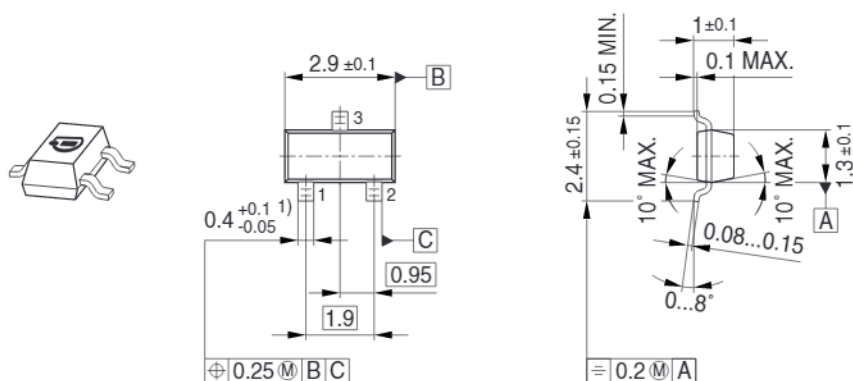
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

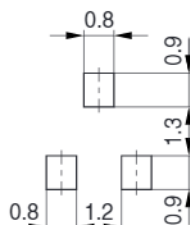


Package Outline

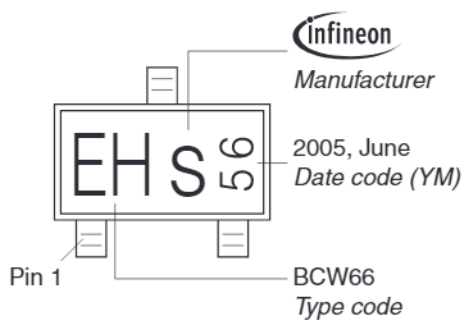


1) Lead width can be 0.6 max. in dambar area

Foot Print

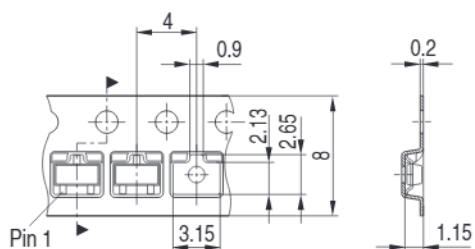


Marking Layout (Example)

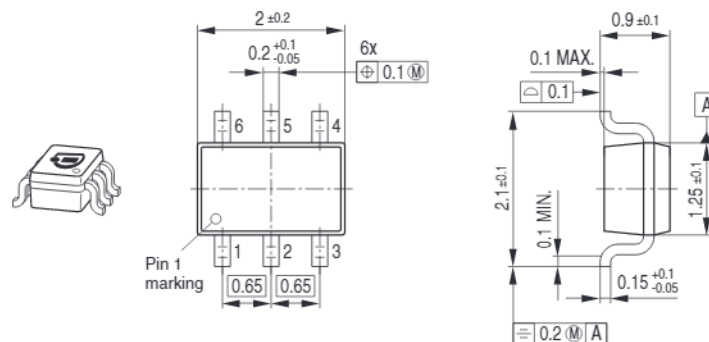


Standard Packing

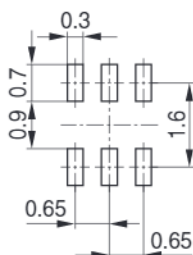
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



Package Outline

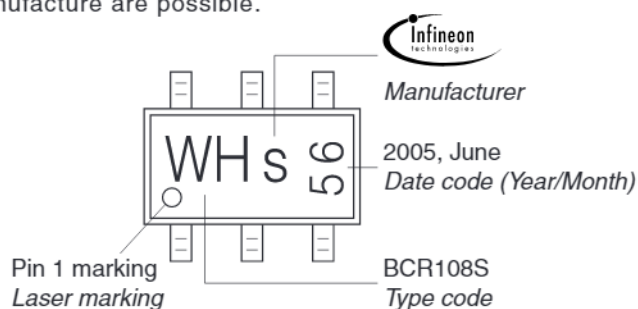


Foot Print



Marking Layout (Example)

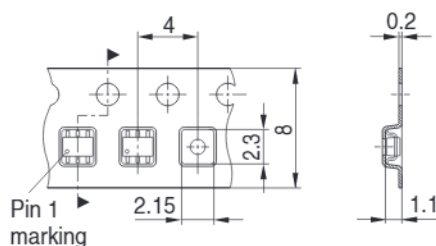
Small variations in positioning of
Date code, Type code and Manufacturer are possible.



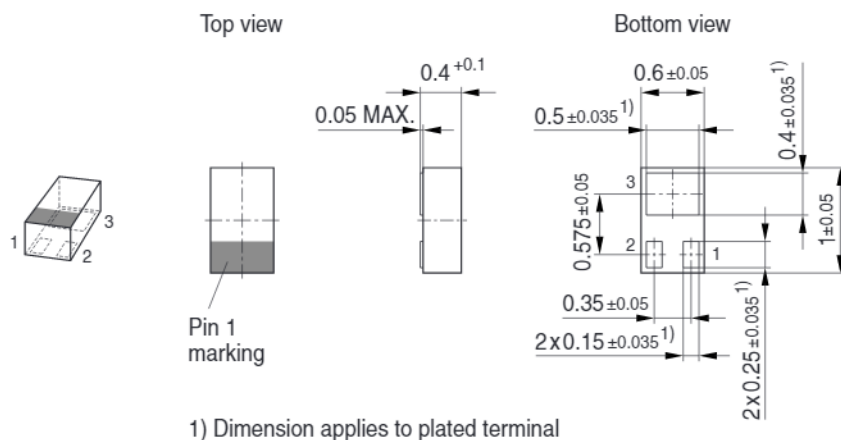
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

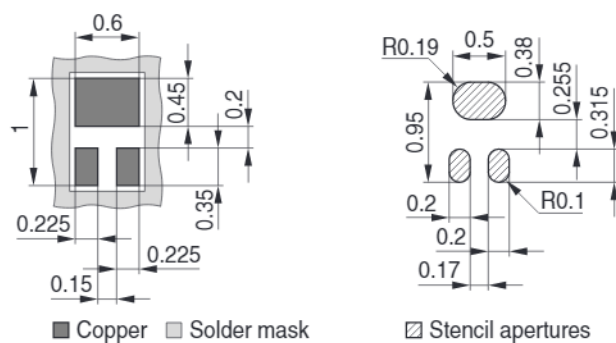


Package Outline

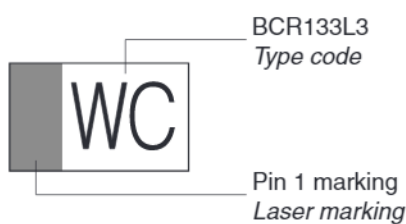


Foot Print

For board assembly information please refer to Infineon website "Packages"

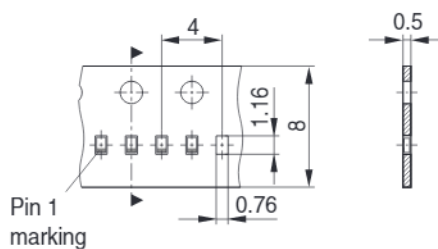


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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